

PMP9474_BOM

Comment	Description	Designator	Footprint	LibRef	Quantity
GRM21BR71H105KA12L	CAP, CERM, 1uF, 50V, +/-10%, X7R, 0805	C1	0805L	GRM21BR71H105KA12L	1
GRM188R71C103KA01D	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0603	C2	0603S	GRM188R71C103KA01D	1
GRM21BR61A226ME44	CAP, CERM, 22uF, 10V, +/-20%, X5R, 0805	C3	0805L	GRM21BR61A226ME44	1
GRM188R61E105KA12D	CAP, CERM, 1uF, 25V, +/-10%, X5R, 0603	C4	0603S	GRM188R61E105KA12D	1
GMK212BJ474KG-T	CAP, CERM, 0.47uF, 35V, +/-10%, X5R, 0805	C5	0805L	GMK212BJ474KG-T	1
C0603C105K4PACTU	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603	C6	0603S	C0603C105K4PACTU	1
GRM188R71E332KA01D	CAP, CERM, 3300pF, 25V, +/-10%, X7R, 0603	C7	0603S	GRM188R71E332KA01D	1
0603YC104JAT2A	CAP, CERM, 0.1uF, 16V, +/-5%, X7R, 0603	C8	0603S	0603YC104JAT2A	1
C4532X7R3D222K	CAP, CERM, 2200pF, 2000V, +/-10%, X7R, 1812	C9	1812	C4532X7R3D222K	1
B1100-13-F	Diode, Schottky, 100V, 1A, SMA	D1	SMA	B1100-13-F	1
SDM10U45-7-F	Diode, Schottky, 45V, 0.1A, SOD-523	D2	SOD-523	SDM10U45-7-F	1
MMSZ5231B-7-F	Diode, Zener, 5.1V, 500mW, SOD-123	D3	SOD-123	MMSZ5231B-7-F	1
TSW-108-07-G-S	Header, 100mil, 8x1, Gold, TH	J1	TSW-108-07-G-S	TSW-108-07-G-S	1
CRCW0603127KFKEA	RES, 127k ohm, 1%, 0.1W, 0603	R1	0603S	CRCW0603127KFKEA	1
CRCW060310R0FKEA	RES, 10.0 ohm, 1%, 0.1W, 0603	R2	0603S	CRCW060310R0FKEA	1
CRCW0603100KFKEA	RES, 100k ohm, 1%, 0.1W, 0603	R3	0603S	CRCW0603100KFKEA	1
CRCW060316K9FKEA	RES, 16.9k ohm, 1%, 0.1W, 0603	R4	0603S	CRCW060316K9FKEA	1
CRCW060310K0FKEA	RES, 10.0k ohm, 1%, 0.1W, 0603	R5	0603S	CRCW060310K0FKEA	1
CRCW06030000Z0EA	RES, 0 ohm, 5%, 0.1W, 0603	R7, R9	0603S	CRCW06030000Z0EA	2
CRCW060346K4FKEA	RES, 46.4k ohm, 1%, 0.1W, 0603	R8	0603S	CRCW060346K4FKEA	1
CRCW06037K32FKEA	RES, 7.32k ohm, 1%, 0.1W, 0603	R19	0603S	CRCW06037K32FKEA	1
MNC-EP-1000SG		T1	EP-1000SG	MNC_EP_1000SG	1
LM5017MR		U1	MRA08A_N	LM5017	1

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